of EEE201

CMOS Digital Integrated Circuits

Department of Electrical & Electronic Engineering Xi'an Jiaotong-Liverpool University (XJTLU)

Thursday, 27th September 2018

□ Silicon p-n junction

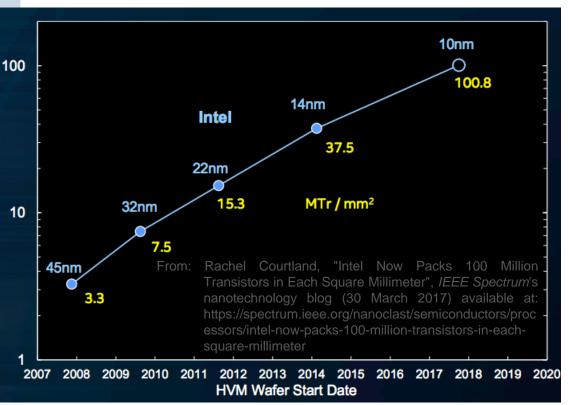
- physical structure
- > electrostatics
- > I-V characteristics & capacitance
- physical layout



Silicon CMOS Digital ICs

(billions of transistors)

☐ In modern digital ICs, a massive number of transistors are packed in a small chip area.



- ➢ In 2018, an Intel microprocessor (e.g. Core i7) contains multibillion transistors.
- ➤ 101 million transistors per mm² in the 10-nm technology node.



Silicon CMOS Digital ICs

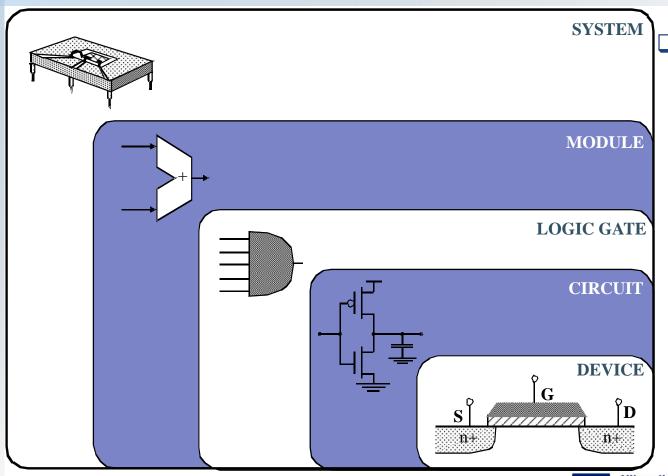
(building blocks for complex construction)

- ☐ One can imagine the huge complexity of digital ICs constructed with billions of transistors.
- No matter how complex the digital IC are, they are still constructed using the fundamental building blocks, namely silicon semiconductor devices.
 - ➤ At the physical layout design level, the major building block is the MOS transistor, with interconnect wires also being essential in connecting different MOS transistors to form complex circuits.

 - > Start from basics in engineering.

Silicon CMOS Digital ICs

(from MOS transistor to complex construction)



□ Silicon **CMOS** digital ICs of whatever complexity start from the **MOS** transistor for their construction.



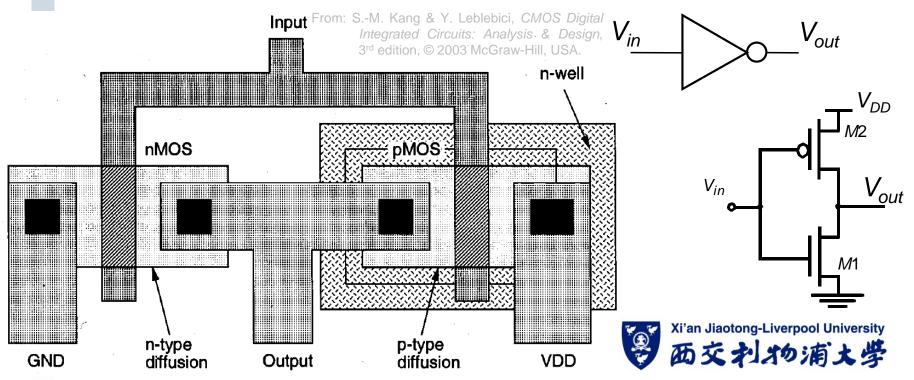
(p-n junction & MOS transistor)

- □ The MOS transistor itself is composed of two fundamental structures in semiconductor electronics, namely the *p-n* junction and the MOS capacitor.
- ☐ The *p-n* junction is essentially a diode from the circuit point of view.
 - > A diode allows current to flow in only one direction.
- The *p-n* junction as a diode is not explicitly used in the silicon CMOS digital ICs (except in the I/O ports' electrostatic discharge protection).
 - > It is everywhere in a silicon CMOS IC.

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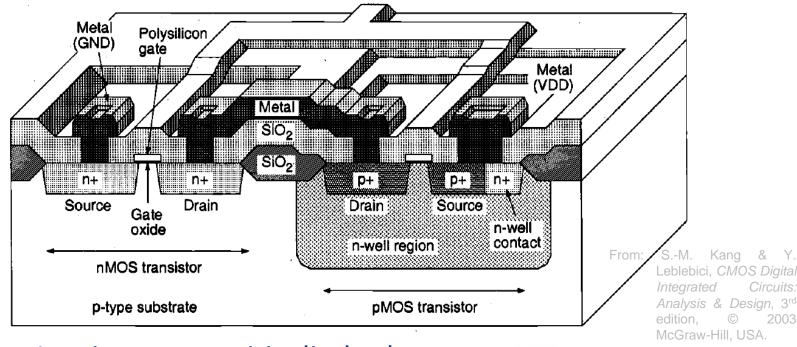
(existence in digital IC)

- □ Two MOS transistors (nMOS and pMOS) are used to construct the fundamental logic gate, inverter.
 - > Do you see where the p-n junctions are in the circuit?



(existence parasitic diode)

 \Box The existence of the *p-n* junction is more obvious when looking at the 3D cross-sectional structure.

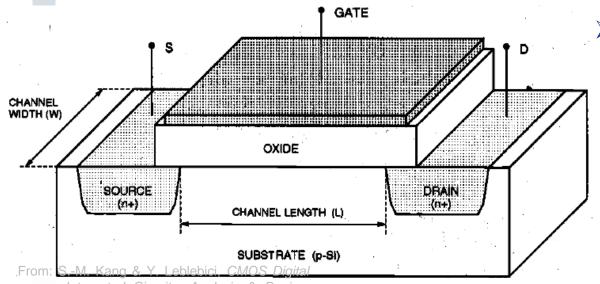


➤ It exists as parasitic diodes but usually reverse-biased.



(normally reverse-biased)

- □ The nMOS transistor (shown here) contains two p-n junctions which do not conduct current in the normal situation as they are reverse-biased.
- ☐ The *p-n* junction however can directly influence the behaviour of the device, not in the static case.

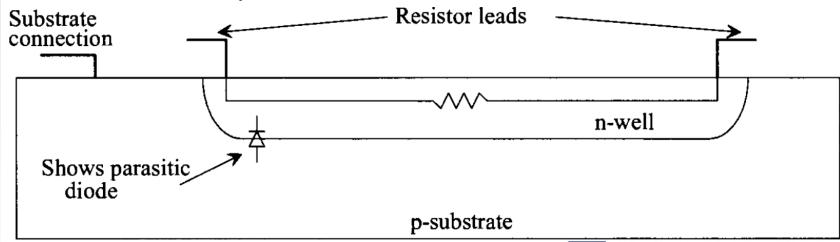


The parasitic capacitance of the p-n junction affects the switching speed of the MOS circuits.



(parasitic diode)

- ☐ In some mixed-signal ICs, integrated resistors may be used in the circuit design.
 - ➤ The implementation of an integrated resistor using an *n*-well on a *p*-substrate contains the *p-n* junction as a distributed parasitic diode.



From: R. Jacob Baker, CMOS: Circuit Design, Layout, and Simulation, 3e, © 2010 Wiley-IEEE Press, USA.



p-n Junction – CMOS implementation

(simplest semiconductor device)

- □ To help the physical layout design of CMOS digital ICs, it is good to know the basic properties and device equations of the p-n junction as a diode.
- □ As the simplest semiconductor device, the p-n junction diode is typically implemented as shown in the cross-sectional diagram here.

From: J. M. Rabaey et al., Digital Integrated Circuits: A Design
Perspective, 2nd edition, © 2003 Pearson, USA.

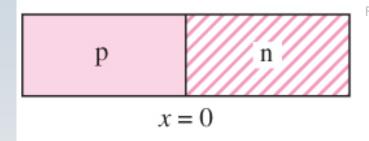
B
Al
SiO₂

➤ The structure consists of a *p*-type region on an *n*-type substrate or vice versa.

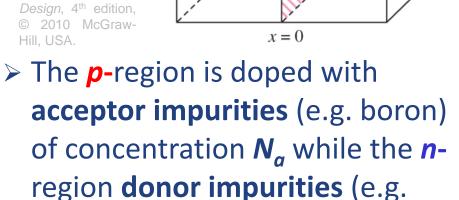


(physical structure)

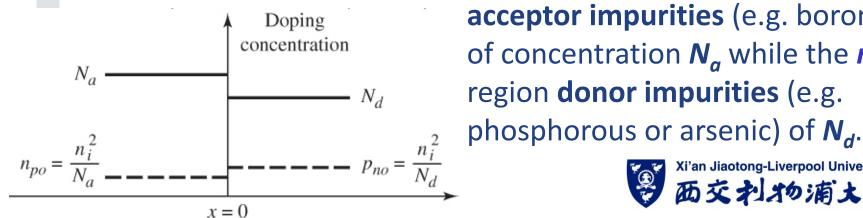
 \square For simplicity of explanations, the p-n junction diode is usually represented by a structure with a Cross-sectional **p**-type block next to an **n**-type. area



From: Donald A. Neamen. Microelectronics: Circuit Analysis & Design, 4th edition, © 2010 McGraw-Hill. USA.



n





(majority & minority carriers)

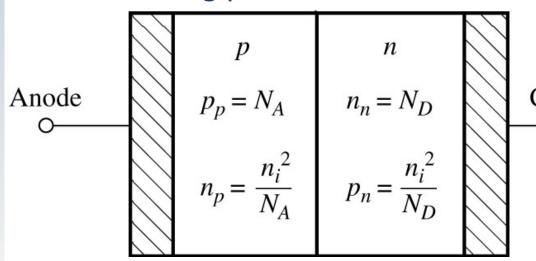
- □ In the *p*-region, there are plenty of holes as the majority carriers, with the hole concentration $p_p \approx N_a$ at room temperature.
 - \triangleright The subscript p in p_p means that it is in the p-region.
- □ In the *n*-region, there are plenty of **electrons** as the **majority carriers**, with the electron concentration $n_n \approx N_d$ at room temperature.
 - \triangleright The subscript n in n_n means that it is in the n-region.
- The minority carrier concentrations are respectively n_p (electron concentration) in the p-region and p_n (hole concentration) in the n-region.

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 - mass action law

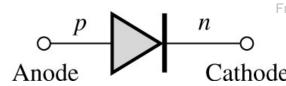
Carrier Concentrations

(mass action law)

- ☐ In thermal equilibrium, the mass action law applies in the p-region as well as in the n-region.
 - ➤ The minority carrier concentrations can be determined accordingly.



Can you distinguish the Cathode different carrier concentrations p_p , p_n , n_p , and n_n ?



From: R. C. Jaeger & T. N. Blalock, Microelectronic Circuit Design, 4e, © 2010 McGraw-Hill, USA.

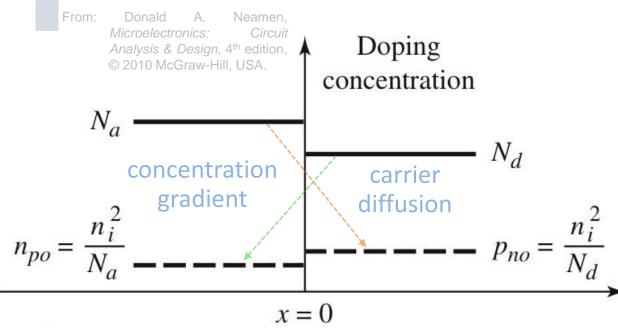


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Concentration Gradient

(carrier diffusion across junction)

□ Due to the large **concentration gradient** in both electrons and holes between the **p**-region and the **n**-region, carrier **diffusion** occurs across the junction and an equilibrium state is reached.



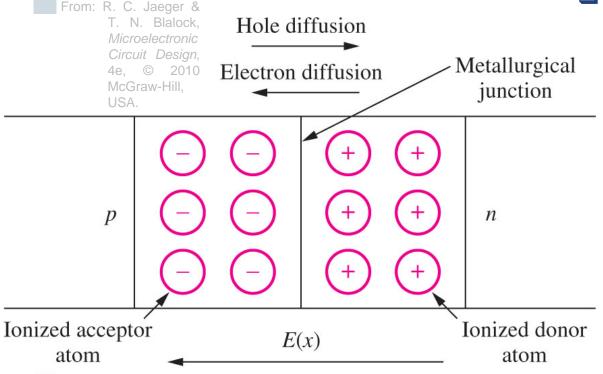
- Holes diffuse from the p-region to the n-region.
- Flectrons diffuse from the *n*-region to the *p*-region



Carrier Diffusion

(immobile dopant ions)

■ When the holes leave the p-type region, they leave behind immobile acceptor dopant ions, which are negatively charged.



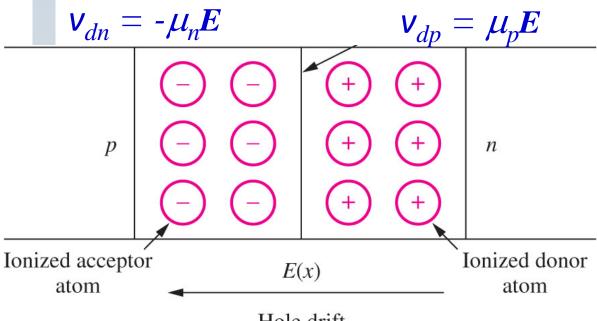
Similarly, when the electrons leave the n-type region, immobile donor dopant ions are left behind and they are positively charged.



Carrier Drift

(electric field from immobile charges)

■ With the opposite charges on the two sides near the boundary of the p-type and n-type regions, an electric field is created.



- From: R. C. Jaeger & T. N. Blalock, *Microelectronic Circuit Design*, 4e, © 2010 McGraw-Hill, USA.
- Hole drift

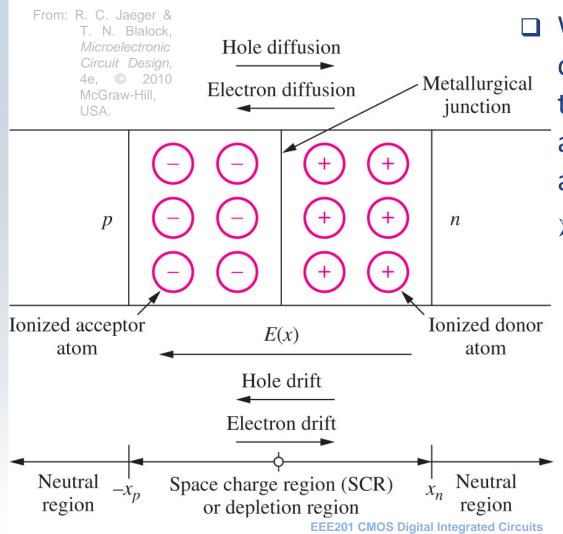
 Electron drift

- > It points from the ntype region to the p-type region.
- ➤ It causes drift action of the charge carriers, opposite to the diffusion direction.



Depletion Region

(equilibrium of drift & diffusion)



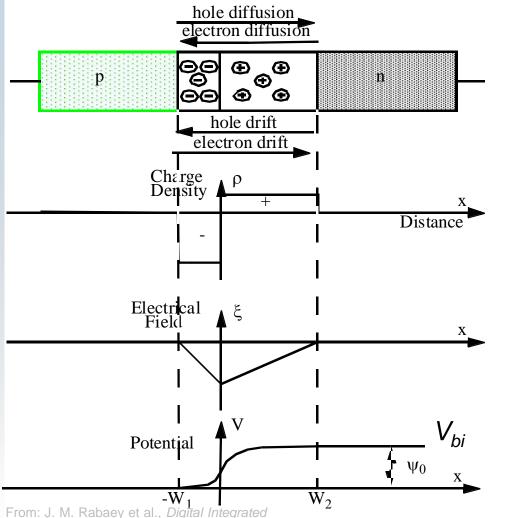
With the drift action counteracting with the carrier diffusion, an equilibrium is attained

A space-charge region or called depletion region is formed at the metallurgical junction.



p-n Junction: Electrostatics

(charge density to electric potential)

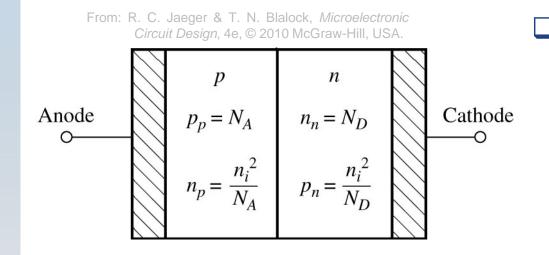


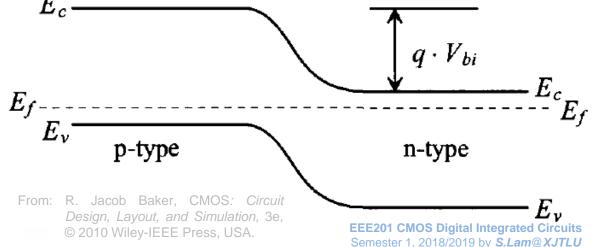
- Using electrostatic analysis, the electric field can be determined from the charge density and the electric potential from the electric field.
- There is a **potential** difference (V_{bi}) between the p-type and n-type regions.



p-n Junction: band diagram

 $(E_f \text{ aligned with each other})$





☐ Using the energy band diagram, the Fermi energy E_f level on the side of the p-type region aligns with that on the side of the ntype region, when an **equilibrium** is reached.



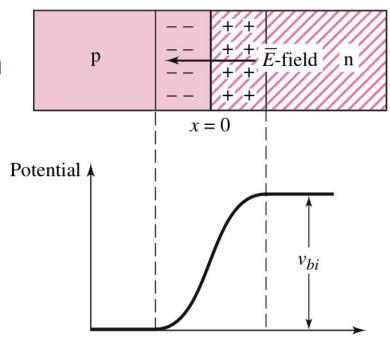
(built-in potential/voltage)

□ The built-in potential or built-in voltage V_{bi} is given by:

$$V_{bi} = \frac{k_B T}{e} \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

$$= V_T \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

- V_T = k_B T/e is called the thermal voltage and V_T ≈ 26 mV at T = 300 K.
- \triangleright **e** is the electronic charge (1.60×10⁻¹⁹ C)



From: Donald A. Neamen, *Microelectronics: Circuit Analysis & Design*, 4th edition, © 2010 McGraw-Hill, USA.



(depletion width)

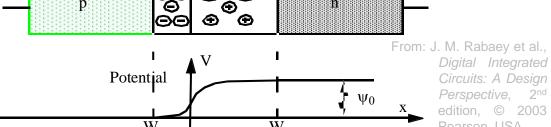
- \square With typical doping concentrations N_D and $N_A \approx$ 10^{16} cm⁻³, V_{hi} is about 0.7 V for the silicon p-njunction at room temperature.
- ☐ As for the width of the **depletion region**, it is given

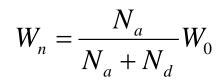
by
$$W_0 = W_p + W_n = \sqrt{\frac{2\varepsilon_{Si}(N_a + N_d)V_{bi}}{eN_aN_d}}$$

$$\geq \text{Note } \varepsilon_{Si} = 11.9\varepsilon_0 = 11.9 \times (8.85 \times 10^{-12} \text{ F/m})$$

$$W_p = \frac{N_d}{N_a + N_d}W_0$$

ightharpoonup Note $\varepsilon_{Si} = 11.9 \varepsilon_0 = 11.9 \times (8.85 \times 10^{-12} \text{ F/m})$

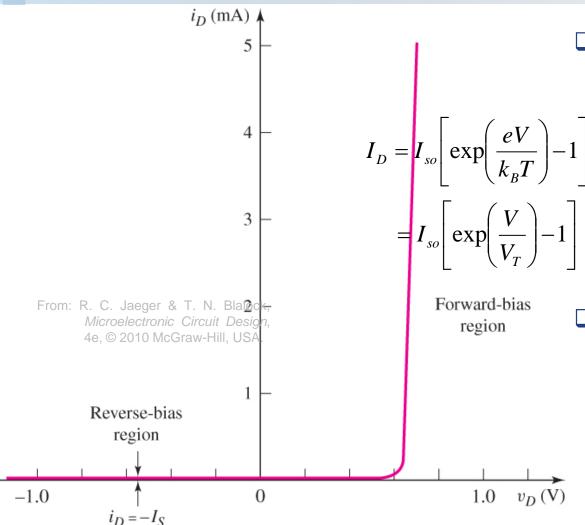






Silicon *p-n* Junction current

(exponential behaviour)



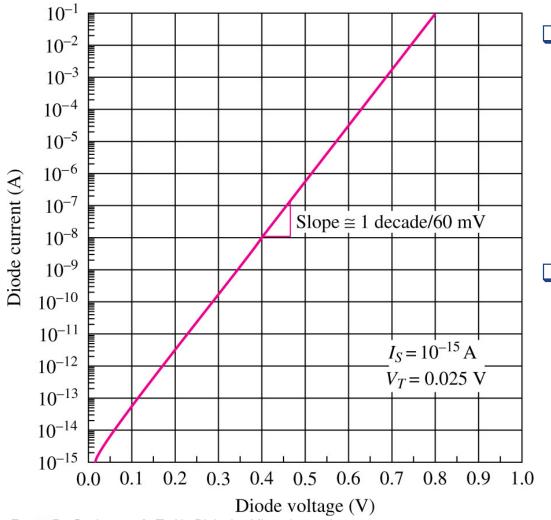
When forward biased, the current flowing through the silicon *p*-n junction diode increases *exponentially*.

When reverse biased, there is only a negligible current.



Silicon *p-n* Junction current

(60 mV per decade)



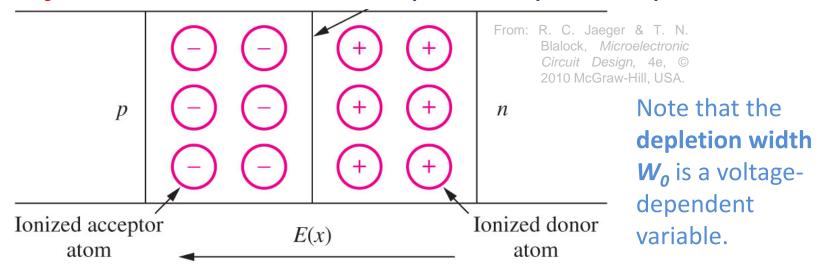
- With the exponential behaviour, the forwardbiased current of the pn junction is a straight line in a semilogarithmic plot.
- □ The inverse of the slope is 60 mV per decade, which is a useful number later for looking at the MOS transistor.



Capacitance of *p-n* Junction

(parallel plate capacitance)

■ With immobile dopant ions of opposite charge on both sides of the metallurgical junction, the *p-n* junction is almost like a parallel-plate capacitor.



In a parallel-plate capacitor, the capacitance is:

$$C = \frac{\mathcal{E}A}{d} \implies C_j = \frac{\mathcal{E}_{Si}A_j}{W_0}$$



Capacitance of *p-n* Junction

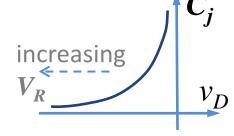
(junction capacitance)

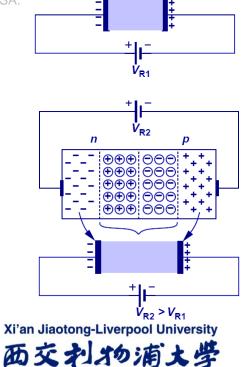
□ Under reverse bias, the *p-n* junction can be viewed as a voltagedependent capacitor. Microelectronics.



- By varying the reverse bias voltage V_R , the depletion width changes, therefore changing the capacitance.
- ☐ This junction capacitance, or called depletion capacitance, can be expressed as

$$C_j = \frac{C_{j0}}{\sqrt{1 + \frac{V_R}{V_{bi}}}}$$

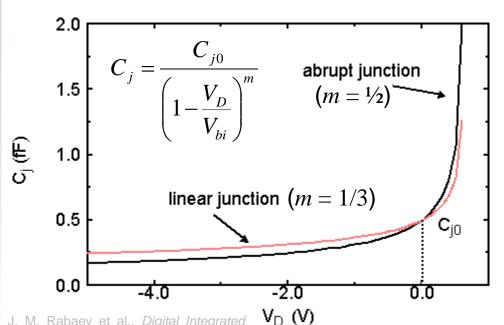




Junction Capacitance

(forward-biased)

□ When forward-biased, the depletion width becomes smaller. As a result, the junction capacitance increases with the forward-bias voltage before reaching the built-in voltage.



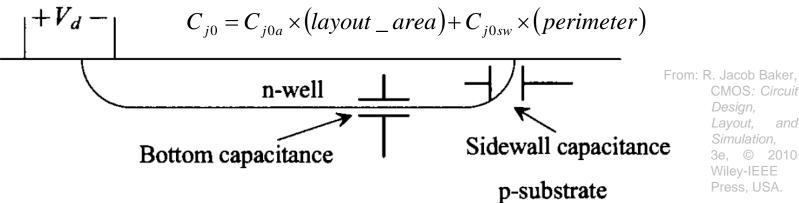
The voltage dependence of the junction capacitance has a slight difference between an abrupt junction and a linear unction.



Junction Capacitance

(sidewall capacitance)

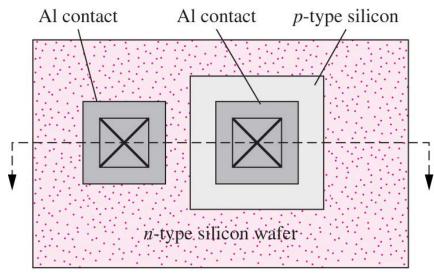
- □ In estimating the junction capacitance in CMOS IC design, the zero-bias junction capacitance C_{j0} needs to be determined first.
- \Box C_{j0} consists of two parts given in the parameter data of a CMOS IC process: one proportional to the area while the other (called **sidewall capacitance**) to the perimeter.



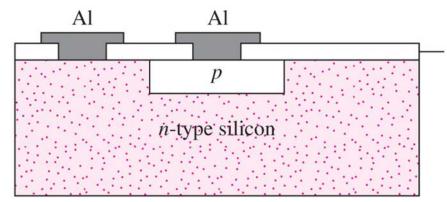
Note: C_{j0a} & C_{j0sw} are normalised capacitances with data provided by the CMOS process.



(simple implementation)



From: R. C. Jaeger & T. N. Blalock, *Microelectronic Circuit Design*, 4e, © 2010 McGraw-Hill, USA.

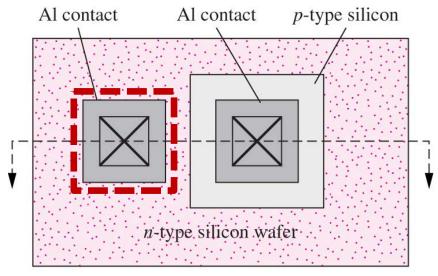


☐ If a *p-n* junction diode is to be designed in a CMOS IC, the **physical** layout is of simple one (for small-current loading) is shown here together with the corresponding cross-sectional structure.

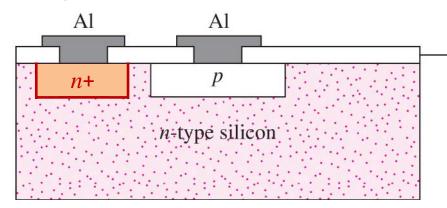
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SiO2

(improved implementation)



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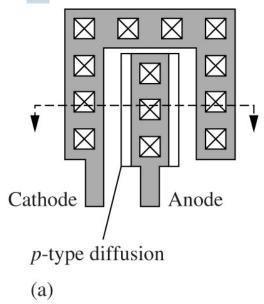


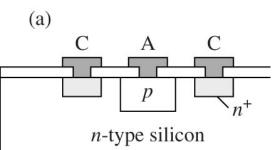
- □ An improvement can be made in the contact of the n-type substrate by using a heavily doped n+ region.
- □ The electrical connection is better in this case because of the so-called ohmic contact.



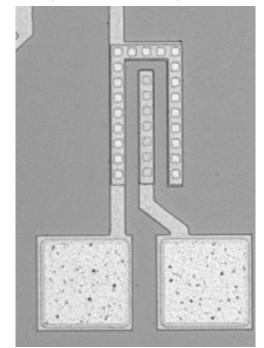
(further improved implementation)

☐ To reduce the series resistance of the *p-n* junction diode, an annular layout can be used.





From: R. C. Jaeger & T. N. Blalock, Microelectronic Circuit Design, 4e, © 2010 McGraw-Hill, USA.



The current can flow in more paths from the anode to the cathode. Such a design can also accommodate a larger diode current. However, the junction capacitance will increase unavoidably.



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